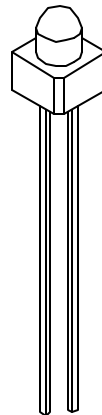
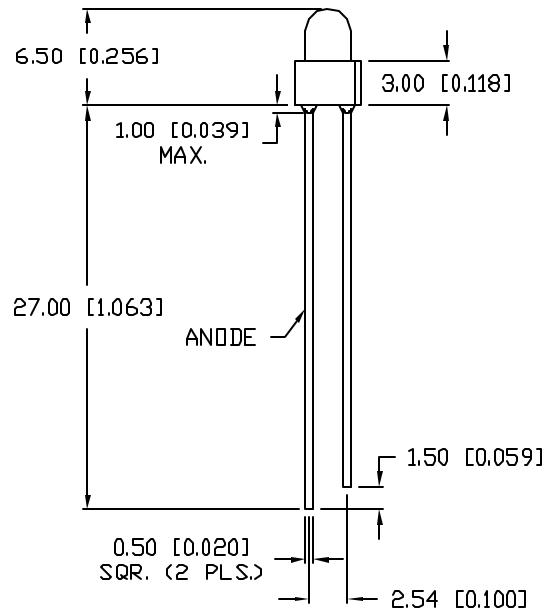
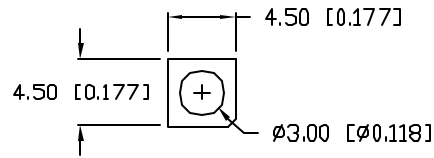


UNCONTROLLED DOCUMENT

PART NUMBER  
SSF-LX3P74YD

REV.  
A

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10BRDR. & REDRAWN IN 3D.	7.18.01



ELECTRO-OPTICAL CHARACTERISTICS  $T_A=25^{\circ}\text{C}$   $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		585		nm	
FORWARD VOLTAGE		2.1	2.5	$V_f$	
REVERSE VOLTAGE	5.0			$V_r$	$I_f=100\mu\text{A}$
AXIAL INTENSITY		25		med	$I_f=20\text{mA}$
VIEWING ANGLE		60		$2x$ theta	
EMITTED COLOR:	YELLOW				
EPOXY LENS FINISH:	YELLOW DIFFUSED				

LIMITS OF SAFE OPERATION AT  $25^{\circ}\text{C}$

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	105	mW
DERATE FROM $25^{\circ}\text{C}$	-1.2	mW/ $^{\circ}\text{C}$
OPERATING, STORAGE TEMP.	-40 TO +85	$^{\circ}\text{C}$
SOLDERING TEMP.	+260	$^{\circ}\text{C}$
2.0mm FROM BODY		3 SEC. MAX

\*  $t < 10\mu\text{s}$

\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X= $\pm 1$  ( $\pm 0.039$ ), XX= $\pm 0.5$  ( $\pm 0.020$ ), XXX= $\pm 0.25$  ( $\pm 0.010$ ), XXXX= $\pm 0.127$  ( $\pm 0.005$ ). LEAD SIZE= $\pm 0.05$  ( $\pm 0.002$ ), LEAD LENGTH= $\pm 0.75$  ( $\pm 0.030$ ), MIN= $\begin{matrix} +0.00 \\ -0.00 \end{matrix}$  DECIMAL PRECISION, MAX= $\begin{matrix} +0.00 \\ -0.00 \end{matrix}$  DECIMAL PRECISION

UNCONTROLLED DOCUMENT

REV. A	PART NUMBER SSF-LX3P74YD
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T-3mm (T-1) ALL EPOXY LED INDICATOR,  
585nm YELLOW LED, YELLOW DIFFUSED.

**RELIABILITY NOTE**  
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: BC	CHECKED BY:	APPROVED BY:	DATE: 9.27.00
			PAGE: 1 OF 1
			SCALE: N/A